ABSTRACT

Disclosed is a semiconductor device consisting of a lead frame or a circuit board, at least one semiconductor element which is stacked on or mounted in parallel on the lead frame or on the circuit board, a copper wire which electrically connects the lead frame or the circuit board to the semiconductor element, and an encapsulating material which encapsulates the semiconductor element and the copper wire, wherein the wire diameter of the copper wire is equal to or more than 18 μm and equal to or less than 23 μm,

the encapsulating material is composed of a cured product of an epoxy resin composition,

the epoxy resin composition contains an epoxy resin (A), a curing agent (B), a spherical silica (C), and a metal hydroxide and/or metal hydroxide solid solution (D), and

the semiconductor device is obtained through a step of encapsulating by the epoxy resin composition and molding, and then segmenting the resultant into pieces.